

CS8182

Micropower 200 mA Low Dropout Tracking Regulator/Line Driver

The CS8182 is a monolithic integrated low dropout tracking regulator designed to provide adjustable buffered output voltage that closely tracks (± 10 mV) the reference input. The output delivers up to 200 mA while being able to be configured higher, lower or equal to the reference voltages.

The output has been designed to operate over a wide range (2.8 V to 45 V) while still maintaining excellent DC characteristics. The CS8182 is protected from reverse battery, short circuit and thermal runaway conditions. The device also can withstand 45 V load dump transients and -50 V reverse polarity input voltage transients. This makes it suitable for use in automotive environments.

The $V_{REF}/ENABLE$ lead serves two purposes. It is used to provide the input voltage as a reference for the output and it also can be pulled low to place the device in sleep mode where it nominally draws less than 30 μ A from the supply.

Features

- 200 mA Source Capability
- Output Tracks within ± 10 mV Worst Case
- Low Dropout (0.35 V Typ. @ 200 mA)
- Low Quiescent Current
- Thermal Shutdown
- Short Circuit Protection
- Wide Operating Range
- Internally Fused Leads in SO-8 Package
- For Automotive and Other Applications Requiring Site and Change Control

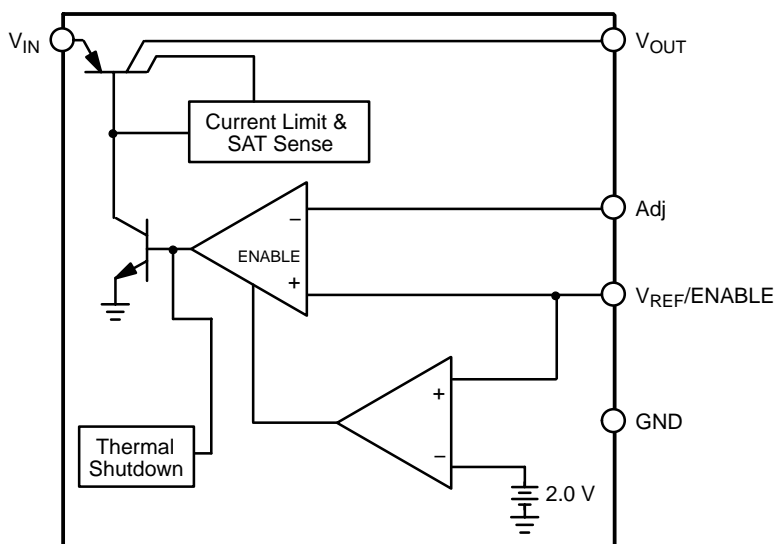


Figure 1. Block Diagram

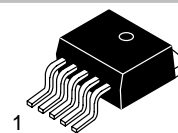


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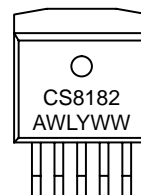
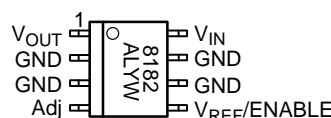


SO-8
DF SUFFIX
CASE 751



D²PAK-5
DPS SUFFIX
CASE 936AC

PIN CONNECTIONS AND MARKING DIAGRAMS



Tab GND
Pin 1. V_{IN}
2. V_{OUT}
3. GND
4. Adj
5. V_{REF}

1

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

ORDERING INFORMATION*

Device	Package	Shipping [†]
CS8182YDF8	SO-8	95 Units/Rail
CS8182YDFR8	SO-8	2500 Tape & Reel
CS8182YDPS5	D ² PAK 5-PIN	50 Units/Rail
CS8182YDPSR5	D ² PAK 5-PIN	750 Tape & Reel

*Consult your local sales representative for SO-8 with exposed pads package option.

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE PIN DESCRIPTION

Package Lead Number		Lead Symbol	Function
SO-8	D ² PAK 5-PIN		
8	1	V _{IN}	Input voltage.
1	2	V _{OUT}	Regulated output.
2, 3, 6, 7	3	GND	Ground.
4	4	Adj	Adjust lead.
5	5	V _{REF} /ENABLE	Reference voltage and ENABLE input.

MAXIMUM RATINGS

Rating	Value	Unit
Storage Temperature	-65 to 150	°C
Supply Voltage Range (continuous)	-15 to 45	V
Supply Voltage Range (normal, continuous)	3.4 to 45	V
Peak Transient Voltage (V _{IN} = 14 V, Load Dump Transient = 31 V)	45	V
Voltage Range (Adj, V _{OUT} , V _{REF} /ENABLE)	-10 to 45	V
Maximum Junction Temperature	150	°C
Package Thermal Resistance, SO-8: Junction-to-Case, R _{θJC} Junction-to-Ambient, R _{θJA}	25 110	°C/W °C/W
Package Thermal Resistance, D ² PAK, 5-Pin: Junction-to-Case, R _{θJC} Junction-to-Ambient, R _{θJA}	4.0 10-50**	°C/W °C/W
ESD Capability (Human Body Model) (Machine Model)	2.0 200	kV V
Lead Temperature Soldering: (Note 1)	Reflow: (SO-8) (D2PAK) 240 peak 225 peak (Note 2)	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. 60 second maximum above 183°C.
2. -5°C/+0°C allowable conditions.

*Depending on thermal properties of substrate. $R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$

CS8182

ELECTRICAL CHARACTERISTICS ($V_{IN} = 14\text{ V}$; $V_{REF}/ENABLE > 2.75\text{ V}$; $-40^{\circ}\text{C} < T_J < +125^{\circ}\text{C}$; $C_{OUT} \geq 10\text{ }\mu\text{F}$; $0.1\text{ }\Omega < C_{OUT-ESR} < 1.0\text{ }\Omega$ @ 10 kHz , unless otherwise specified.)

Parameter	Test Conditions	Min	Typ	Max	Unit
Regular Output					
$V_{REF} - V_{OUT}$ V_{OUT} Tracking Error	$4.5\text{ V} \leq V_{IN} \leq 26\text{ V}$, $100\text{ }\mu\text{A} \leq I_{OUT} \leq 200\text{ mA}$, Note 3 $V_{IN} = 12\text{ V}$, $I_{OUT} = 30\text{ mA}$, $V_{REF} = 5.0\text{ V}$, Note 3	-10 -5.0	- -	10 5	mV mV
Dropout Voltage ($V_{IN} - V_{OUT}$)	$I_{OUT} = 100\text{ }\mu\text{A}$ $I_{OUT} = 30\text{ mA}$ $I_{OUT} = 200\text{ mA}$	- - -	100 - 350	150 500 600	mV mV mV
Line Regulation	$4.5\text{ V} \leq V_{IN} \leq 26\text{ V}$, Note 3	-	-	10	mV
Load Regulation	$100\text{ }\mu\text{A} \leq I_{OUT} \leq 200\text{ mA}$, Note 3	-	-	10	mV
Adj Lead Current	Loop in Regulation	-	0.2	1.0	μA
Current Limit	$V_{IN} = 14\text{ V}$, $V_{REF} = 5.0\text{ V}$, $V_{OUT} = 90\%$ of V_{REF} , Note 3	225	-	700	mA
Quiescent Current ($I_{IN} - I_{OUT}$)	$V_{IN} = 12\text{ V}$, $I_{OUT} = 200\text{ mA}$ $V_{IN} = 12\text{ V}$, $I_{OUT} = 100\text{ }\mu\text{A}$ $V_{IN} = 12\text{ V}$, $V_{REF}/ENABLE = 0\text{ V}$	- - -	15 75 30	25 150 55	mA μA μA
Reverse Current	$V_{OUT} = 5.0\text{ V}$, $V_{IN} = 0\text{ V}$	-	0.2	1.5	mA
Ripple Rejection	$f = 120\text{ Hz}$, $I_{OUT} = 200\text{ mA}$, $4.5\text{ V} \leq V_{IN} \leq 26\text{ V}$	60	-	-	dB
Thermal Shutdown	GBD	150	180	210	$^{\circ}\text{C}$
$V_{REF}/ENABLE$					
Enable Voltage	-	0.80	2.00	2.75	V
Input Bias Current	$V_{REF}/ENABLE$	-	0.2	1.0	μA

3. V_{OUT} connected to Adj lead.

TYPICAL CHARACTERISTICS

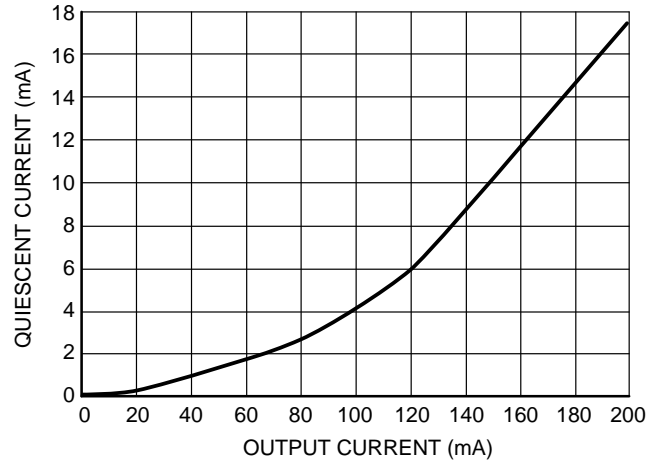


Figure 2. Quiescent Current vs. Output Current

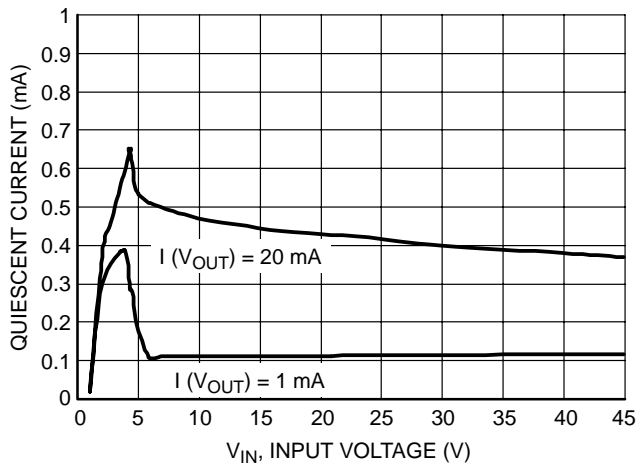


Figure 3. Quiescent Current vs. Input Voltage (Operating Mode)

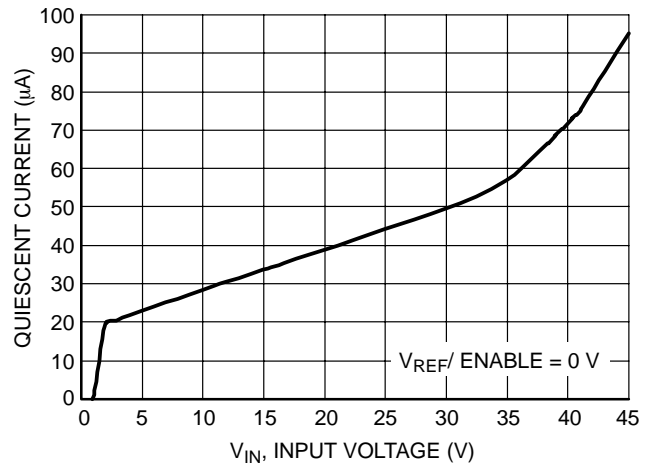


Figure 4. Quiescent Current vs. Input Voltage (Sleep Mode)

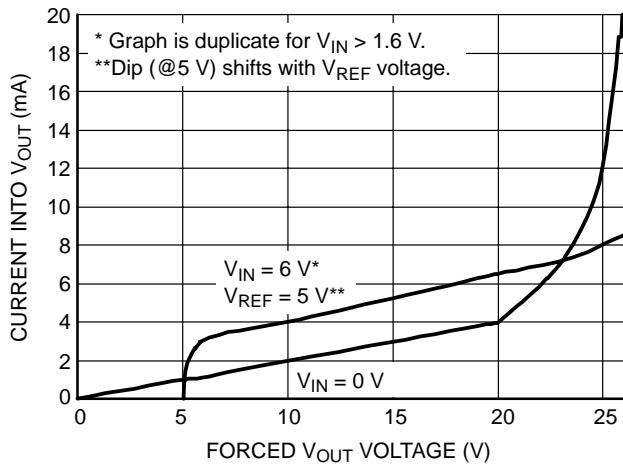


Figure 5. V_{OUT} Reverse Current

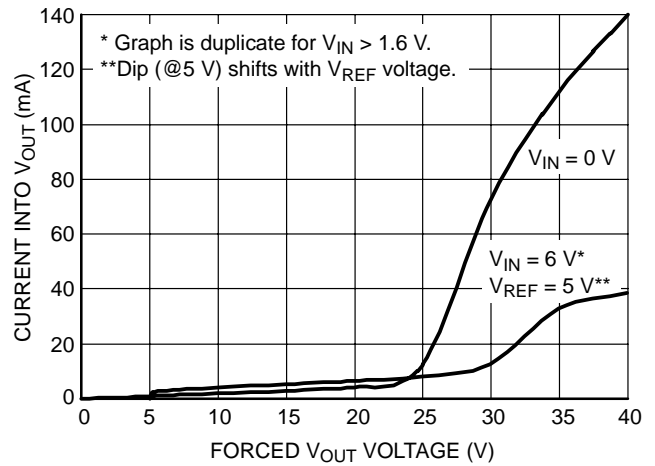


Figure 6. V_{OUT} Reverse Current

CIRCUIT DESCRIPTION

ENABLE Function

By pulling the $V_{REF}/ENABLE$ lead below 2.0 V typically, (see Figure 10 or Figure 11), the IC is disabled and enters a sleep state where the device draws less than 55 μA from supply. When the $V_{REF}/ENABLE$ lead is greater than 2.75 V, V_{OUT} tracks the $V_{REF}/ENABLE$ lead normally.

Output Voltage

The output is capable of supplying 200 mA to the load while configured as a similar (Figure 7), lower (Figure 9), or higher (Figure 8) voltage as the reference lead. The Adj lead acts as the inverting terminal of the op amp and the V_{REF} lead as the non-inverting.

The device can also be configured as a high-side driver as displayed in Figure 12.

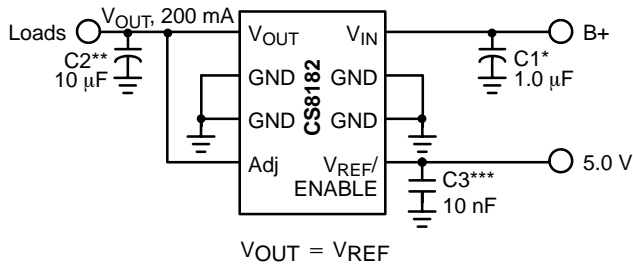


Figure 7. Tracking Regulator at the Same Voltage

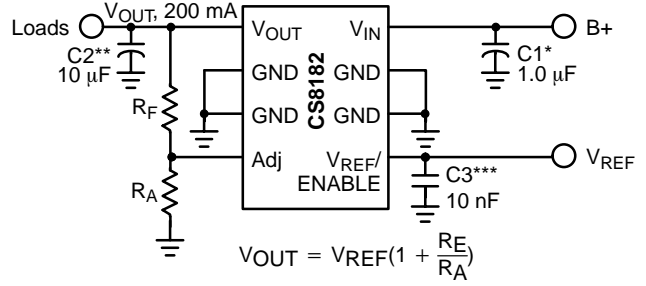


Figure 8. Tracking Regulator at Higher Voltages

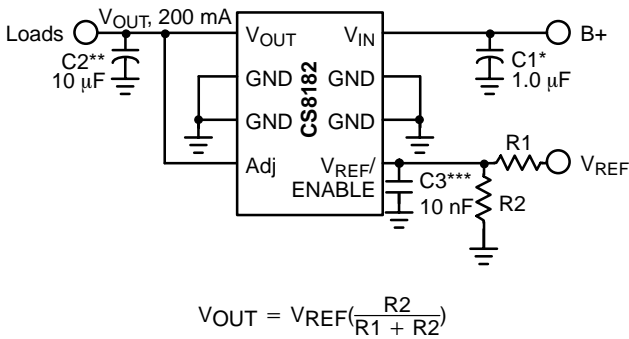


Figure 9. Tracking Regulator at Lower Voltages

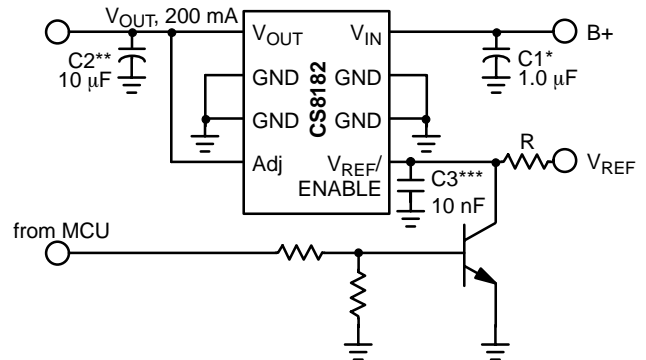


Figure 10. Tracking Regulator with ENABLE Circuit

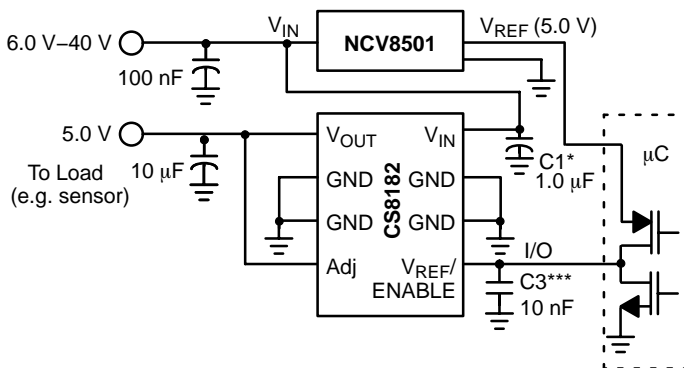


Figure 11. Alternative ENABLE Circuit

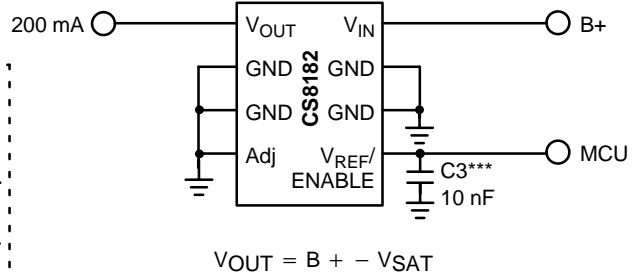


Figure 12. High-Side Driver

* C1 is required if the regulator is far from the power source filter.

** C2 is required for stability.

*** C3 is recommended for EMC susceptibility.

APPLICATION NOTES

V_{OUT} Short to Battery

The CS8182 will survive a short to battery when hooked up the conventional way as shown in Figure 13. No damage to the part will occur. The part also endures a short to battery when powered by an isolated supply at a lower voltage as in

Figure 14. In this case the CS8182 supply input voltage is set at 7 V when a short to battery (14 V typical) occurs on V_{OUT} which normally runs at 5 V. The current into the device (ammeter in Figure 14) will draw additional current as displayed in Figure 15.

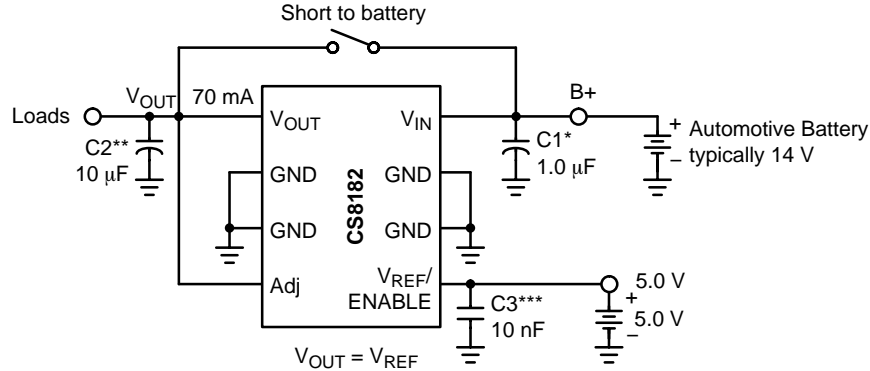
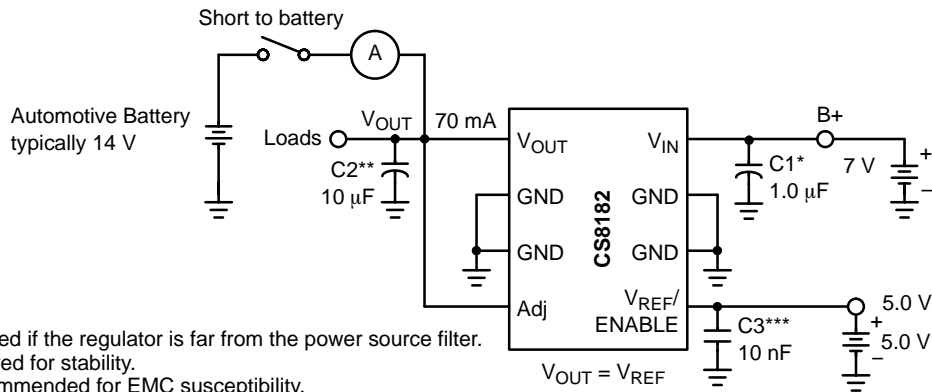


Figure 13.



* C1 is required if the regulator is far from the power source filter.
 ** C2 is required for stability.
 *** C3 is recommended for EMC susceptibility.

Figure 14.



Figure 15. V_{OUT} Short to Battery

Switched Application

The CS8182 has been designed for use in systems where the reference voltage on the V_{REF}/ENABLE pin is continuously on. Typically, the current into the V_{REF}/ENABLE pin will be less than 1.0 μA when the voltage on the V_{IN} pin (usually the ignition line) has been switched out (V_{IN} can be at high impedance or at ground.) Reference Figure 16.

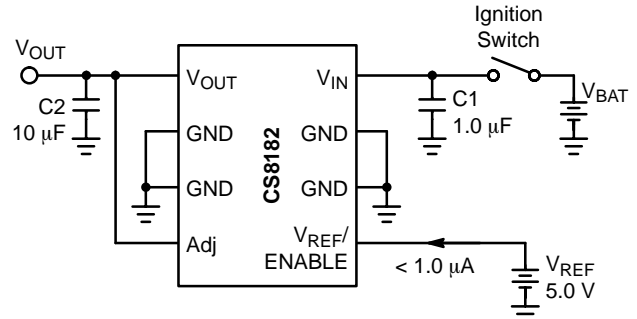


Figure 16.

External Capacitors

The output capacitor for the CS8182 is required for stability. Without it, the regulator output will oscillate. Actual size and type may vary depending upon the application load and temperature range. Capacitor effective series resistance (ESR) is also a factor in the IC stability. Worst-case is determined at the minimum ambient temperature and maximum load expected.

The output capacitor can be increased in size to any desired value above the minimum. One possible purpose of this would be to maintain the output voltage during brief conditions of negative input transients that might be characteristic of a particular system.

The capacitor must also be rated at all ambient temperatures expected in the system. To maintain regulator stability down to -40°C , a capacitor rated at that temperature must be used.

More information on capacitor selection for SMART REGULATOR®s is available in the SMART REGULATOR application note, "Compensation for Linear Regulators," document number SR003AN/D, available through our website at <http://www.onsemi.com>.

Calculating Power Dissipation in a Single Output Linear Regulator

The maximum power dissipation for a single output regulator (Figure 17) is:

$$\text{PD(max)} = \{V_{\text{IN(max)}} - V_{\text{OUT(min)}}\} I_{\text{OUT(max)}} + V_{\text{IN(max)}} I_{\text{Q}} \quad (1)$$

where:

$V_{\text{IN(max)}}$ is the maximum input voltage,

$V_{\text{OUT(min)}}$ is the minimum output voltage,

$I_{\text{OUT(max)}}$ is the maximum output current, for the application, and

I_{Q} is the quiescent current the regulator consumes at $I_{\text{OUT(max)}}$.

Once the value of PD(max) is known, the maximum permissible value of $R_{\theta\text{JA}}$ can be calculated:

$$R_{\theta\text{JA}} = \frac{150^{\circ}\text{C} - T_{\text{A}}}{\text{PD}} \quad (2)$$

The value of $R_{\theta\text{JA}}$ can then be compared with those in the package section of the data sheet. Those packages with $R_{\theta\text{JA}}$'s less than the calculated value in equation 2 will keep the die temperature below 150°C .

In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heat sink will be required.

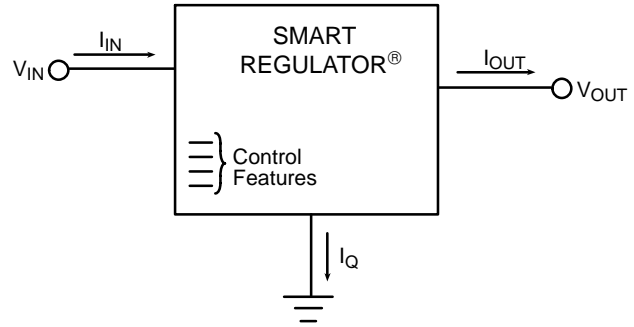


Figure 17. Single Output Regulator with Key Performance Parameters Labeled

Heatsinks

A heatsink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of $R_{\theta\text{JA}}$:

$$R_{\theta\text{JA}} = R_{\theta\text{JC}} + R_{\theta\text{CS}} + R_{\theta\text{SA}} \quad (3)$$

where:

$R_{\theta\text{JC}}$ = the junction-to-case thermal resistance,

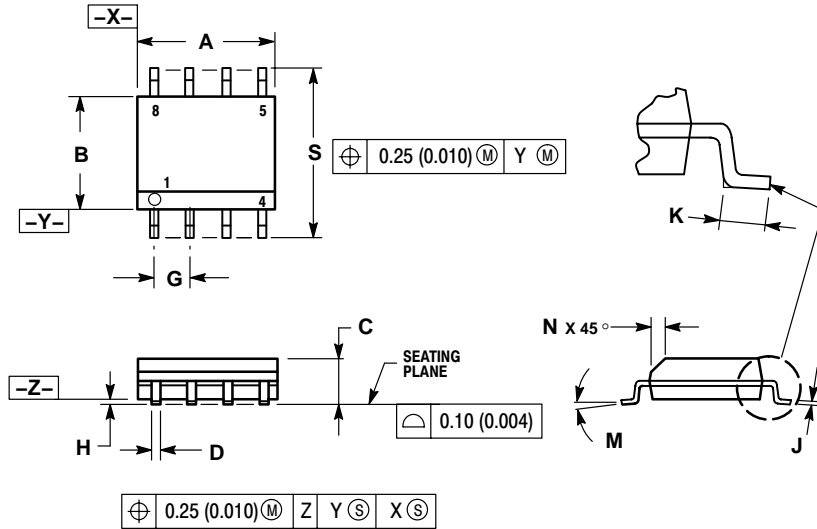
$R_{\theta\text{CS}}$ = the case-to-heatsink thermal resistance, and

$R_{\theta\text{SA}}$ = the heatsink-to-ambient thermal resistance.

$R_{\theta\text{JC}}$ appears in the package section of the data sheet. Like $R_{\theta\text{JA}}$, it is a function of package type. $R_{\theta\text{CS}}$ and $R_{\theta\text{SA}}$ are functions of the package type, heatsink and the interface between them. These values appear in heat sink data sheets of heatsink manufacturers.

PACKAGE DIMENSIONS

SOIC-8
DF SUFFIX
CASE 751-07
ISSUE AB



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT

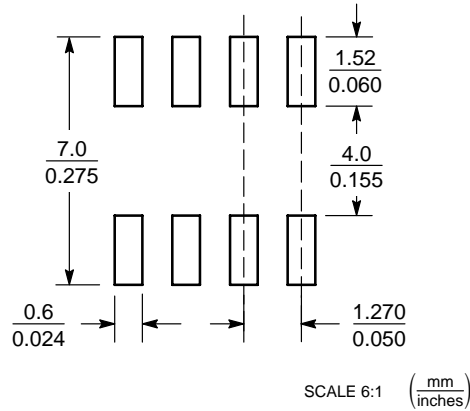
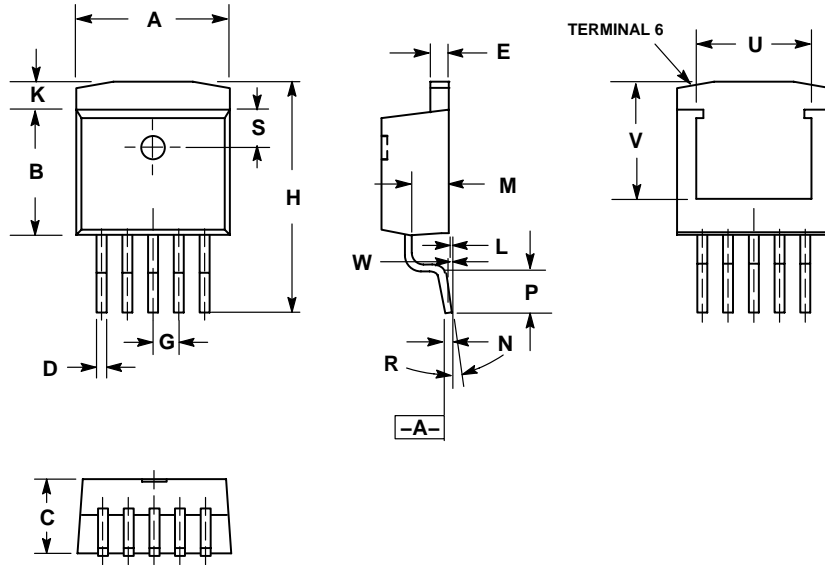


Figure 18. SOIC-8

PACKAGE DIMENSIONS


D²PAK-5
DP SUFFIX
CASE 936AC-01
ISSUE O



- NOTES:
1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASH AND METAL BURR.
 4. PACKAGE OUTLINE INCLUSIVE OF PLATING THICKNESS.
 5. FOOT LENGTH MEASURED AT INTERCEPT POINT BETWEEN DATUM A AND LEAD SURFACE.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.396	0.406	10.05	10.31
B	0.330	0.340	8.38	8.64
C	0.170	0.180	4.31	4.57
D	0.026	0.036	0.66	0.91
E	0.045	0.055	1.14	1.40
G	0.067 REF		1.70 REF	
H	0.580	0.620	14.73	15.75
K	0.055	0.066	1.40	1.68
L	0.000	0.010	0.00	0.25
M	0.098	0.108	2.49	2.74
N	0.017	0.023	0.43	0.58
P	0.090	0.110	2.29	2.79
R	0 °	8 °	0 °	8 °
S	0.095	0.105	2.41	2.67
U	0.30 REF		7.62 REF	
V	0.305 REF		7.75 REF	
W	0.010		0.25	

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